

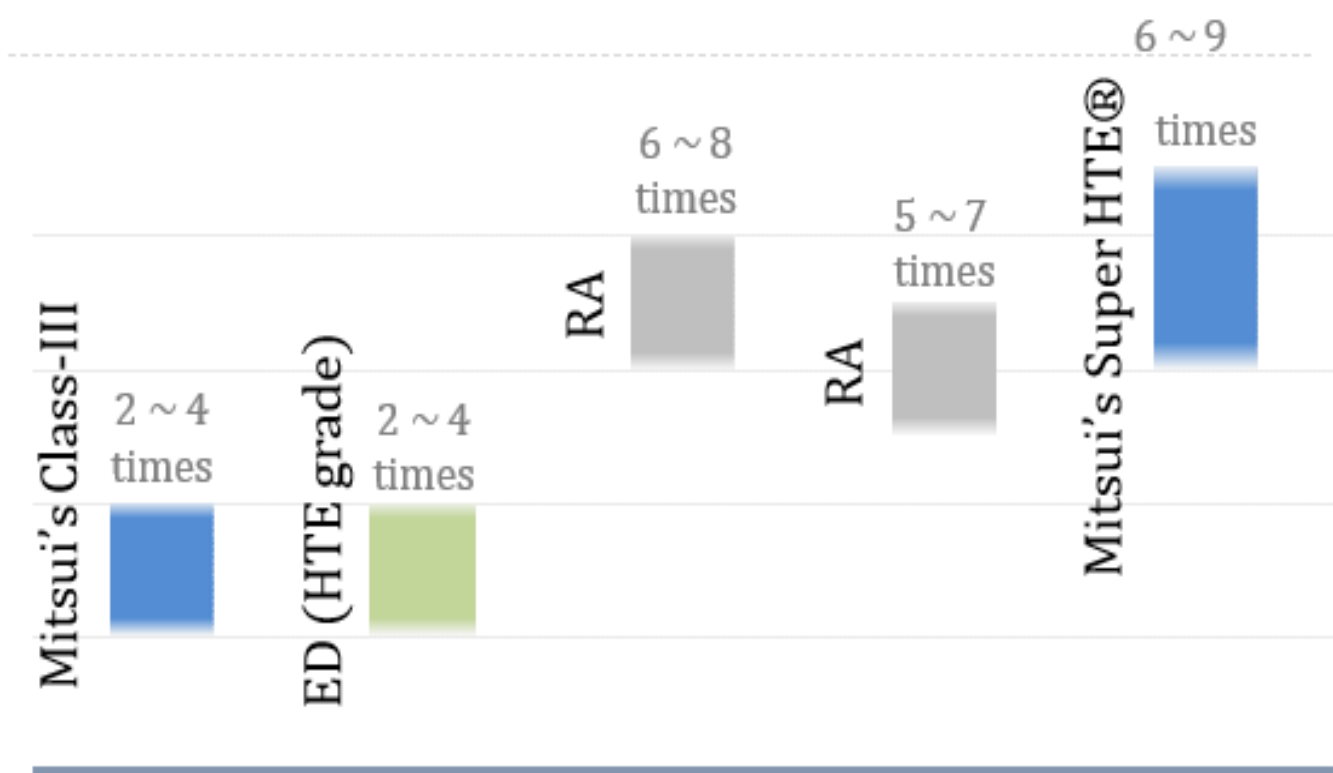
# Super HTE<sup>®</sup>系列

## 兩層/三層軟性基板適用的低溫退火電解銅箔

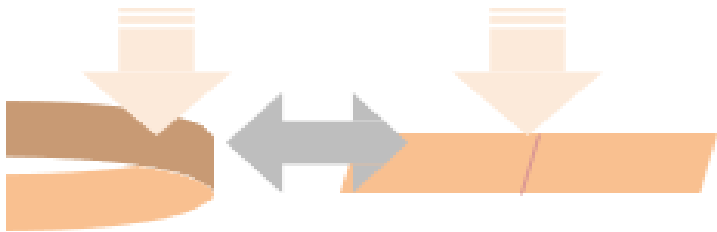
Low temperature annealing ED Copper Foil for 2Layer/3Layer FCCL

### S-HTE Series : 3EC-M2S-HTE<sup>®</sup> & 3EC-M3S-HTE<sup>®</sup>

#### 死折繞曲特性 Dead-fold flexibility

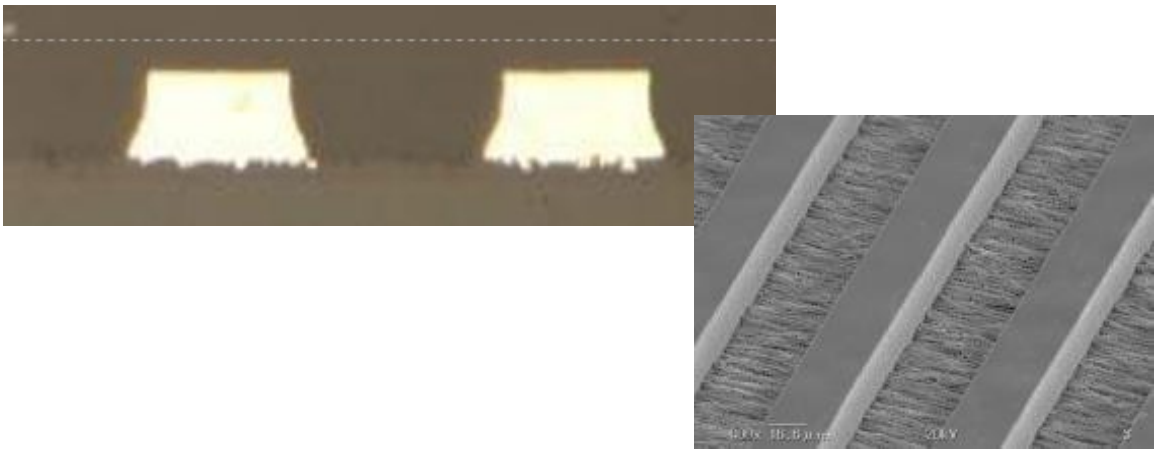


- 等同於壓延銅箔的死折繞曲特性  
Equivalent dead-fold flexibility performance to RA foil
- 比一般HTE電解銅箔有更優異的繞折特性  
Advantageous flexibility to conventional HTE grade ED foil



- 條件:
- 兩層雙面板(12 $\mu$ m/1mil/12 $\mu$ m)
  - 銅箔寬度1cm
  - 下壓力10kgf

#### 細線路的蝕刻特性 Etching performance for fine line



- L/S = 45/35 $\mu$ m的線路成形可達到3.5左右的蝕刻因子  
(線高20 $\mu$ m, 銅箔厚度12 $\mu$ m)
- Etching factor marked 3.5 around when forming L/S=45/35 $\mu$ m circuitry on 20 $\mu$ m thick Cu  
(=12 $\mu$ m foil & plating)
- \*\* 9 $\mu$ m 3EC-M2S-HTE able to perform excellent Etching Performance for Fine Line Patterning.
- \*\* 9 $\mu$ m 3EC-M2S-HTE, 對微細線路成形特別顯得優越

Super HTE Series	Surface Roughness Lam. Side [ $\mu$ m ]	Cross Section Image	Thickness [ $\mu$ m ]
3EC-M2S-HTE <sup>®</sup>	Rz 1.8		9 $\mu$ m
3EC-M3S-HTE <sup>®</sup>	Rz 2.5		12 $\mu$ m / 18 $\mu$ m / 35 $\mu$ m

\* Mass Production in Mitsui Copper Foil Malaysia plant.

#### 銅箔具優越特性，適用於高端軟板應用

#### Excellent Copper Foil characteristic for Advance Flexible Board application.

- ◎ 三井特產之超高延展性銅箔，擁有優越的柔軟特性及繞折表現。
- ◎ 翻轉銅瘤化處理之超低粗度，對微細線路成形特別顯得優越。
- ◎ 超低粗度特性對高頻高速運用上，具優良訊號傳輸及低損耗的功能。
- ◎ 具備充足及全面可靠的產能，確保滿足客戶需求。
- ◎ Mitsui proprietary Super-HTE copper foil with excellent flexural characteristic and bending performance.
- ◎ Reversed-Treated copper foil with lower profile on bonding surface which has excellent advantages on fine circuit.
- ◎ Excellent performance in Signal lost for High Speed High frequency FPCB application.
- ◎ Good track record of reliable and advance production capability to fulfil customers' volume requirement.



三井金屬